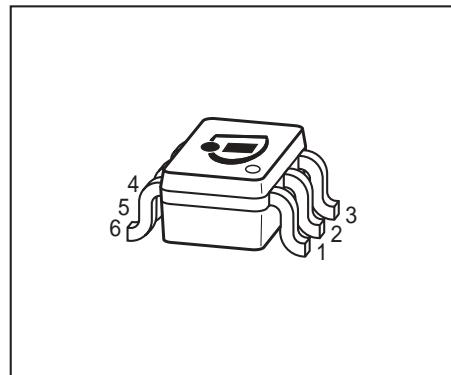
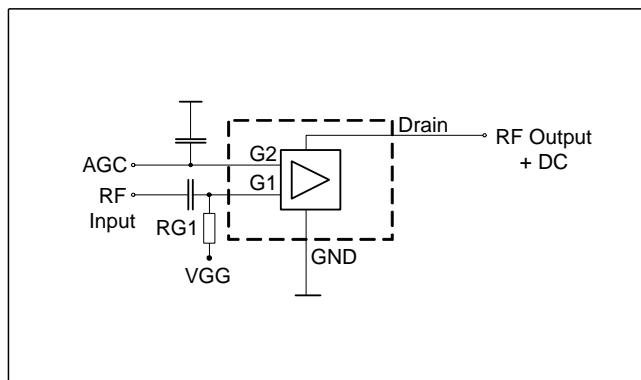
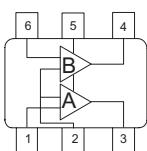


DUAL N-Channel MOSFET Tetrode

- Two gain controlled input stage for UHF and VHF -tuners e.g. (NTSC, PAL)
- Two AGC amplifiers in one single package
- Integrated gate protection diodes
- High AGC-range, low noise figure, high gain
- Improved cross modulation at gain reduction
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101


**BG3130
BG3130R**

ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Type	Package	Pin Configuration						Marking
BG3130	SOT363	1=G1*	2=G2	3=D*	4=D**	5=S	6=G1**	KAs
BG3130R	SOT363	1=G1*	2=S	3=D*	4=D**	5=G2	6=G1**	KHs

* For amp. A; ** for amp. B

180° rotated tape loading orientation available

Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	8	V
Continuous drain current	I_D	25	mA
Gate 1/ gate 2-source current	$\pm I_{G1/2SM}$	1	
Gate 1/ gate 2-source voltage	$\pm V_{G1/G2S}$	6	V
Total power dissipation	P_{tot}	200	mW
Storage temperature	T_{stg}	-55 ... 150	°C
Channel temperature	T_{ch}	150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Channel - soldering point ¹⁾	R_{thchs}	≤ 280	K/W

¹For calculation of R_{thJA} please refer to Application Note Thermal Resistance

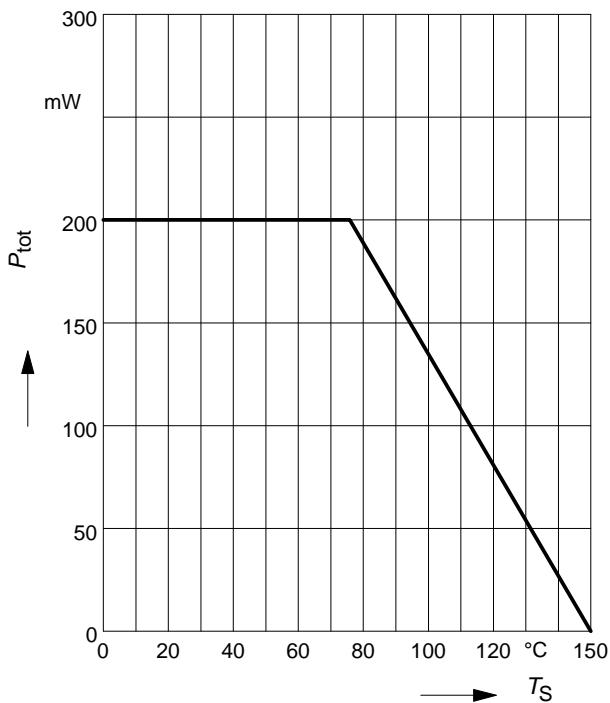
Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Drain-source breakdown voltage $I_D = 10 \mu\text{A}, V_{G1S} = 0 \text{ V}, V_{G2S} = 0 \text{ V}$	$V_{(\text{BR})\text{DS}}$	12	-	-	V
Gate1-source breakdown voltage $+I_{G1S} = 10 \text{ mA}, V_{G2S} = 0 \text{ V}, V_{\text{DS}} = 0 \text{ V}$	$+V_{(\text{BR})\text{G1SS}}$	6	-	15	
Gate2-source breakdown voltage $+I_{G2S} = 10 \text{ mA}, V_{G1S} = 0 \text{ V}, V_{\text{DS}} = 0 \text{ V}$	$+V_{(\text{BR})\text{G2SS}}$	6	-	15	
Gate1-source leakage current $V_{G1S} = 6 \text{ V}, V_{G2S} = 0 \text{ V}$	$+I_{\text{G1SS}}$	-	-	50	μA
Gate2-source leakage current $V_{G2S} = 8 \text{ V}, V_{G1S} = 0 \text{ V}, V_{\text{DS}} = 0 \text{ V}$	$+I_{\text{G2SS}}$	-	-	50	nA
Drain current $V_{\text{DS}} = 5 \text{ V}, V_{G1S} = 0 \text{ V}, V_{G2S} = 4.5 \text{ V}$	I_{DSS}	-	-	10	μA
Drain-source current $V_{\text{DS}} = 5 \text{ V}, V_{G2S} = 4 \text{ V}, R_{\text{G1}} = 120 \text{ k}\Omega$	I_{DSX}	-	10	-	mA
Gate1-source pinch-off voltage $V_{\text{DS}} = 5 \text{ V}, V_{G2S} = 4 \text{ V}, I_D = 20 \mu\text{A}$	$V_{\text{G1S(p)}}$	-	0.7	-	V
Gate2-source pinch-off voltage $V_{\text{DS}} = 5 \text{ V}, I_D = 20 \mu\text{A}$	$V_{\text{G2S(p)}}$	-	0.6	-	

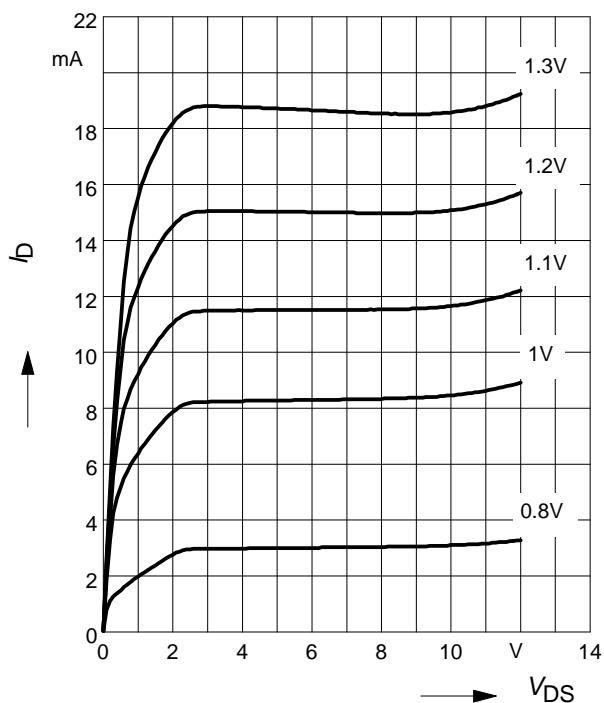
Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics $V_{DS} = 5\text{V}$, $V_{G2S} = 4\text{V}$, ($I_D = 14 \text{ mA}$) (verified by random sampling)					
Forward transconductance	g_{fs}	-	33	-	mS
Gate1 input capacitance $f = 10 \text{ MHz}$	C_{g1ss}	-	1.9	-	pF
Output capacitance $f = 10 \text{ MHz}$	C_{dss}	-	1.1	-	
Power gain $f = 800 \text{ MHz}$ $f = 45 \text{ MHz}$	G_p	- -	24 31	-	dB
Noise figure $f = 800 \text{ MHz}$ $f = 45 \text{ MHz}$	F	- -	1.3 1.7	-	dB
Gain control range $V_{G2S} = 4 \dots 0 \text{ V}$, $f = 800 \text{ MHz}$	ΔG_p	45	-	-	
Cross-modulation $k=1\%$, $f_w=50\text{MHz}$, $f_{unw}=60\text{MHz}$ AGC = 0 dB AGC = 10 dB AGC = 40 dB	X_{mod}	90 - 96	- 87 100	-	-

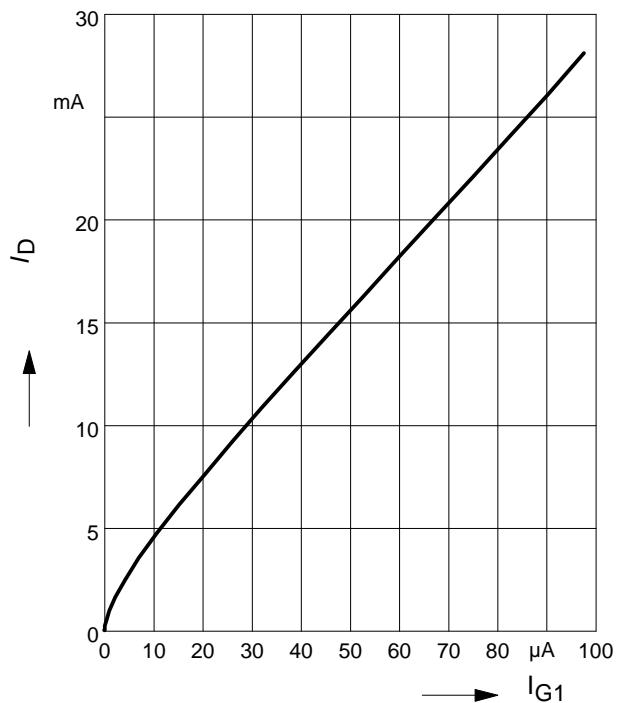
Total power dissipation $P_{\text{tot}} = f(T_S)$
amp. A = amp. B



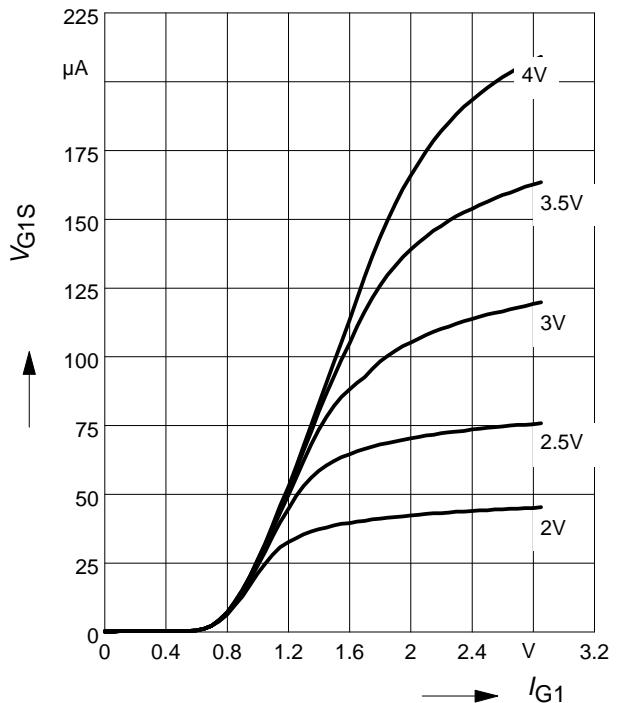
Output characteristics $I_D = f(V_{DS})$
amp. A = amp. B



Drain current $I_D = f(I_{G1})$
 $V_{G2S} = 4V$
amp. A = amp. B

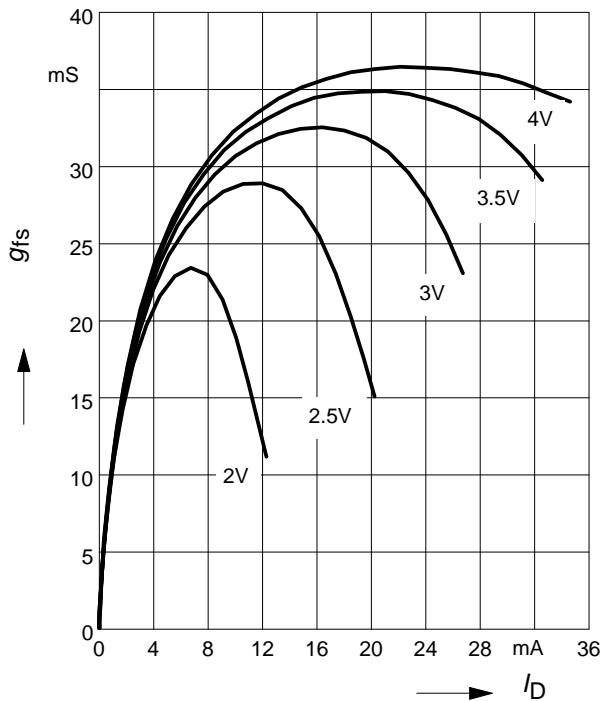


Gate 1 current $I_{G1} = f(V_{G1S})$
 $V_{DS} = 5V$, V_{G2S} = Parameter
amp. A = amp. B

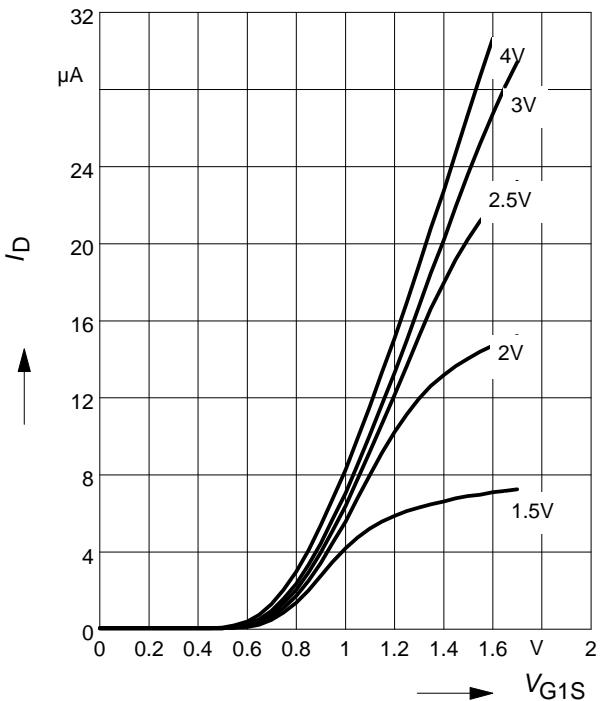


Gate 1 forward transconductance

$g_{fs} = f(I_D)$, $V_{DS} = 5V$, V_{G2S} = Parameter
amp. A = amp. B

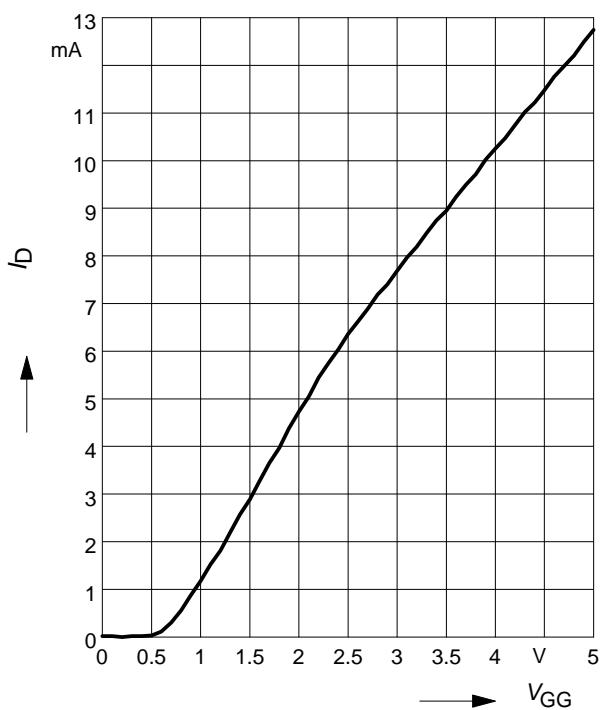

Drain current $I_D = f(V_{G1S})$

$V_{DS} = 5V$, V_{G2S} = Parameter
amp. A = amp. B


Drain current $I_D = f(V_{GG})$ amp.A=amp.B

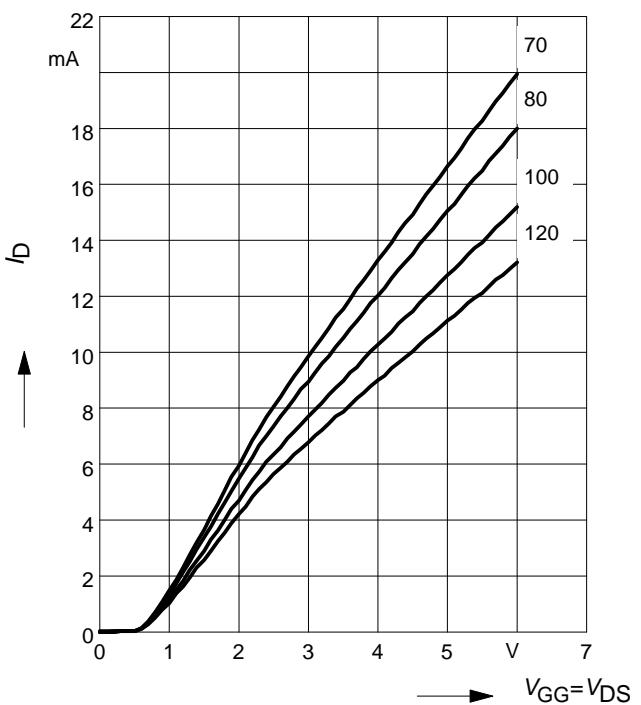
$V_{DS} = 5V$, $V_{G2S} = 4V$, $R_{G1} = 120k\Omega$

(connected to V_{GG} , V_{GG} =gate1 supply voltage)


Drain current $I_D = f(V_{GG})$

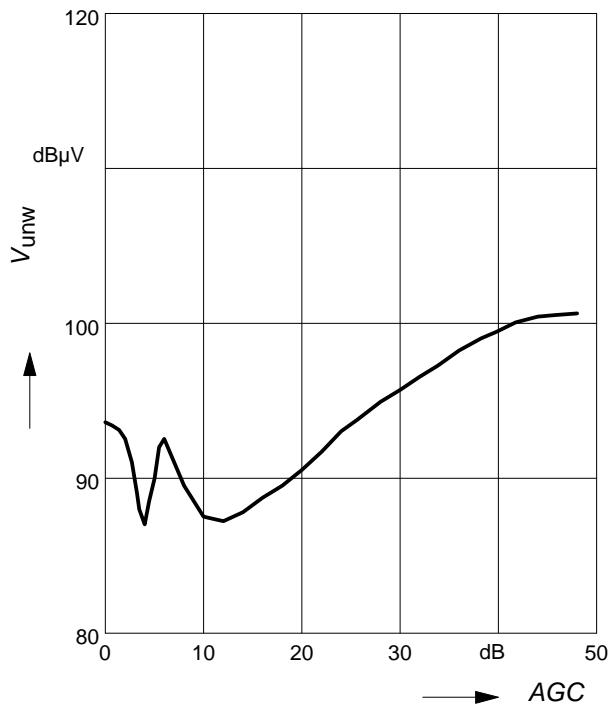
$V_{G2S} = 4V$, R_{G1} = Parameter in kΩ

amp. A = amp. B

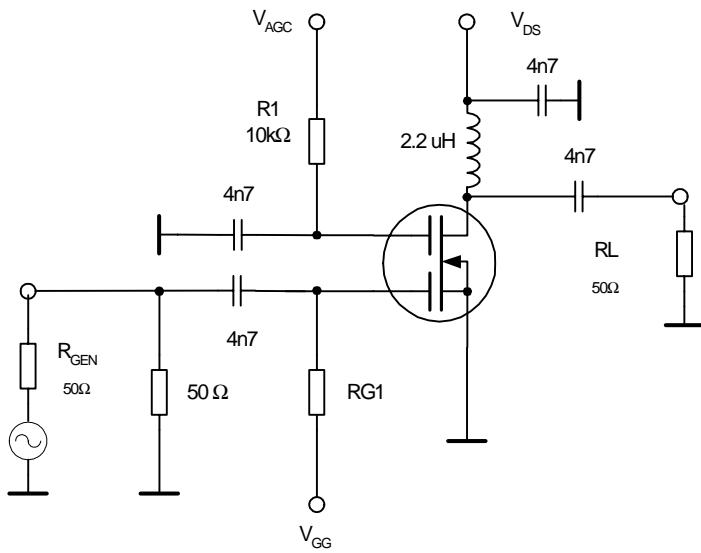


Crossmodulation $V_{\text{unw}} = (\text{AGC})$

$V_{\text{DS}} = 5 \text{ V}$, $R_{\text{g1}} = 68 \text{ k}\Omega$

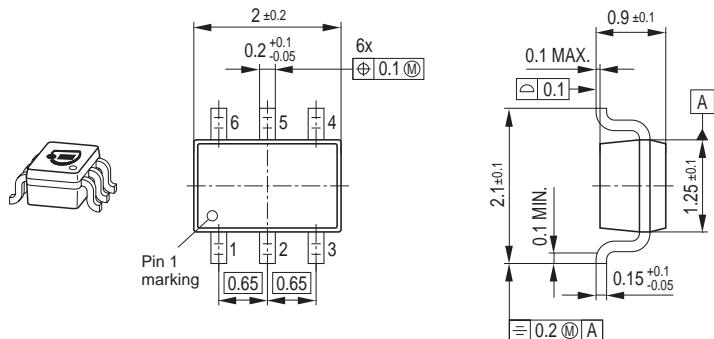


Crossmodulation test circuit

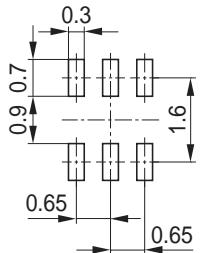


Semibiased

Package Outline

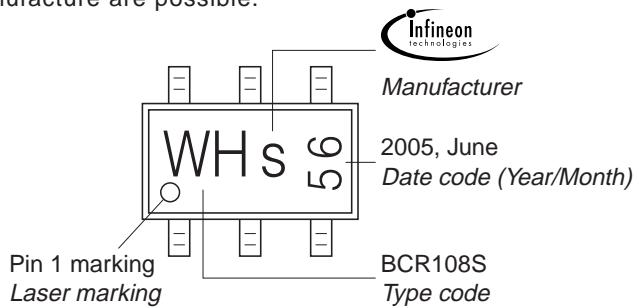


Foot Print



Marking Layout (Example)

Small variations in positioning of Date code, Type code and Manufacture are possible.

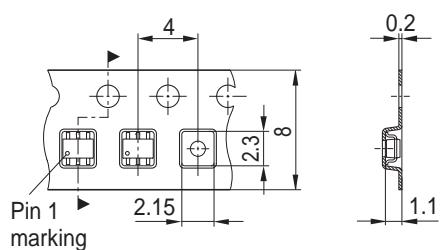


Standard Packing

Reel $\varnothing 180$ mm = 3.000 Pieces/Reel

Reel $\varnothing 330$ mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.



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